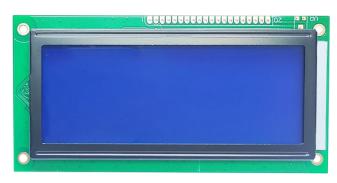


# **RG19264**

# **DISPLAY 192×64 BLUE**





## 1. Features:

The features of LCD are as follows:

• Display mode : STN /BLUE, NEGATIVE, TRANSMISSIVE

• Colour : Display dot : WHITE

Background: BLUE

• Display Format : 192x64

• \* IC : SBN0064

• Interface Input Data : 8 Bits

• Driving Method : 1/64 Duty, 1/9 Bias

• Viewing Direction: 6 O'clock

• Backlight: LED (WHITE)

# 2. Mechanical Specifications:

Item	Specification	Unit
Module Size	130.00(W) X65.00(H) X12.4(T)	mm
Viewing Area	104.00(W) X 39.00(H)	mm
Effective Display Area	97.49(W) X32.46(H)	mm
Number of Dots	192x64	-
Dot Size	0.458(W) X 0.458(H)	mm
Dot Pitch	0.508(W) X 0.508(H)	mm



# 3. Electrical Specifications:

## 1. Absolute Maximum Ratings (Vss = 0V)

Item	Symbol	Sta	andard V	alue	Unit
item	Cymbol	Min.	Тур.	Max.	Offic
Supply Voltage For Logic	Vdd	-0.3	-	5.0	V
Supply Voltage For LCD Drive	Vo, Vout	-0.3	-	14.5	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Тѕт	-30	-	+80	°C
Static Electricity	Be s	sure that you	are grour	nd when handii	ng LCM

#### 2. Electrical Characteristics:

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Supply Voltage	For Logic	VDD – VSS	Ta=25℃	4.8	5.0	5.2	<b>V</b>
Supply Voltage	e For LCD	VDD — Vo	<b>Ta=25</b> ℃	4.6	4.8	5.0	٧
	"H" Level	V <sub>IH</sub>	Ta=25°C	0.8VDD	-	Vdd	V
Input Voltage	"L" Level	V <sub>IL</sub>	1 <b>a-25</b> C	Vss	-	0.2Vdd	V
Output Voltage	"H" Level	V он	$I_{OUT} = -0.5 \text{mA}$	0.8VDD	-	VDD	V
"L" Level		V ol	I <sub>OUT</sub> = 0.5mA	Vss	ı	0.2VDD	V
Current Cons	umption	I <sub>DD</sub>	$V_{IN} = V_{DD}$	-	-	1.0	mA

NOTE: 1) Duty ratio=1/65, Bias=1/9

2) Measured in Dots ON-state

#### 3. BACKLIGHT:

## **3.1** Absolute Maximum Ratings:

Item	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Current	IF	- Ta= 25°C	-	-	20	mA
Reverse Voltage	VR	1a=25 C	-	-	5	V
Power Dissipation	PD	Ta= 25℃	-	-	100	mW

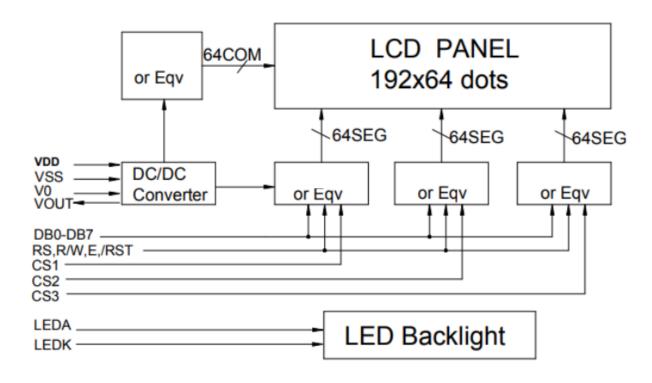
## **3.2** Opto-electronic Characteristics:

Item	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	Ta= 25℃	4.8	5.0	5.2	V
Luminous	-	IF= 30mA	100	150	-	cd/m²

<sup>\*</sup> The brightness is measured without LCD panel



# 4. Schematic Design:





# **5. Interface Pin Function:**

ITEM	SYMBOL	LEVEL	FUNCTION	
1	VSS	0V	Power Ground	
2	VDD	5V	Power Supply For Logic	
3	V0	(*)	Contrast Adjust	
4	RS	H/L	H: Data L: Command	
5	R/W	H/L	H: Read L: Write	
6	Е	H, H->L	Enable Signal	
7	DB0			
$\sim$	~	H/L	Data Bus	
14	DB7			
15	/CS1	L	Chip Selection A	
16	/RST	L	Reset Signal	
17	/CS2	L	Chip Selection B	
18	/CS3	L	Chip Selection C	
19	Vout	17.1	Negative Power output For LCD Driving	
20	LEDA	5V	Power Supply For LED Backlight	



# 6. Command List:

		_	y /		Co	de						
Instructions	RS	RW	780	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function	Note
Display on/off	0	0	0	0	1	1	1	1	1	1/0	Controls the display on or off. Internal status and display data in RAM is not affected 0=off, 1=on	*2
Set Column (Y) Address	0	0	0	1	,	Y ac	idre	ss ((	0-63	)	Set the Column address into the Y address counter	*2
Set Page (X) Address	0	0	1	0	1	1	1		ddr (0-7	ess )	Set the Page address into the X address register	*2
Set Display Start Line (Z address)	0	0	1	1		2		dres 63)	is		Indicates the display data RAM displayed at the top of the screen	*2
Status Read	0	1	Busy	0	Jo/uo	Reset	0	0	0	0	Read status Busy=L, Driver ready; Busy=H, Driver busy on/off=L, Display is on; on/off=H, Display is off Reset=L, Normal Running; Reset=H, reset	*1
Write Display Data	1	0			٧	Vrite	da	ta			Write display data into display data RAM, After writing instruction, Y address counter increased by 1 automatically	*2
Read Display Data	1	1			F	lead	d da	ta			Read display data form the display data RAM	*1

## Note:

- 1\*. Only one section(driver) could be read at the same time.
- 2\*. For the details of the display control instructions, please refer to SBN0064G datasheet.



# 7. Timing Characteristics (Continued):

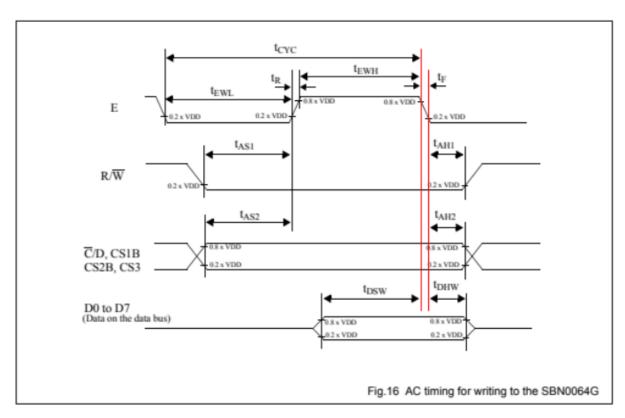
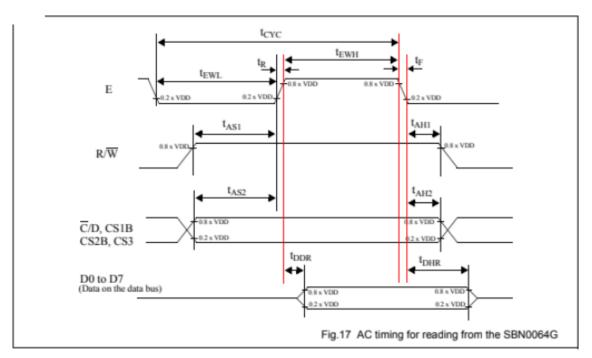


Table 25 AC timing for writing to the SBN0064G

 $V_{DD}$  = 5 V ±10%;  $V_{SS}$  = 0 V;  $T_{amb}$  = -20 °C to +75°C.

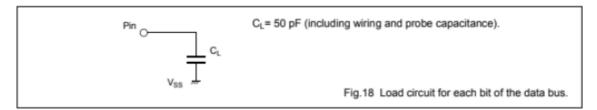
symbol	parameter	min.	max.	test conditions	unit
t <sub>CYC</sub>	Enable (E) cycle time	1000			
t <sub>EWL</sub>	Enable (E) LOW width	450			
t <sub>EWH</sub>	Enable (E) HIGH width	450			
t <sub>R</sub>	Enable (R) rise time		20		
t <sub>F</sub>	Enable (F) fall time		20		1
t <sub>AS1</sub>	Write set-up time	140			ns
t <sub>AH1</sub>	Write hold time	10			]
tas2	C/D, CS1B, CS2B, CS3 set-up time	140			1
t <sub>AH2</sub>	C/D, CS1B, CS2B, CS3 hold time	10			1
t <sub>DSW</sub>	Data setup time (on the data bus)	200		The loading on	1
t <sub>DHW</sub>	Data hold time (on the data bus)	10		the data bus is shown in Fig. 18.	





**Table 26** AC timing for reading from the SBN0064G  $V_{DD}$  = 5 V ±10%;  $V_{SS}$  = 0 V;  $T_{amb}$  = -20 °C to +75°C.

symbol	parameter	min.	max.	test conditions	unit
t <sub>CYC</sub>	Enable (E) cycle time	1000			
t <sub>EWL</sub>	Enable (E) LOW width	450			]
t <sub>EWH</sub>	Enable (E) HIGH width	450			
t <sub>R</sub>	Enable (R) rise time		20		
t <sub>F</sub>	Enable (F) fall time		20		1
t <sub>AS1</sub>	READ set-up time	140			ns
t <sub>AH1</sub>	READ hold time	20			1
t <sub>AS2</sub>	C/D, CS1B, CS2B, CS3 set-up time	140			1
t <sub>AH2</sub>	C/D, CS1B, CS2B, CS3 hold time	10			1
t <sub>DDR</sub>	Data delay time (on the data bus)	320		The loading on	1
t <sub>DHR</sub>	Data hold time (on the data bus)	20		the data bus is shown in Fig. 18.	



#### 13.2 CLK1, CLK2 timing

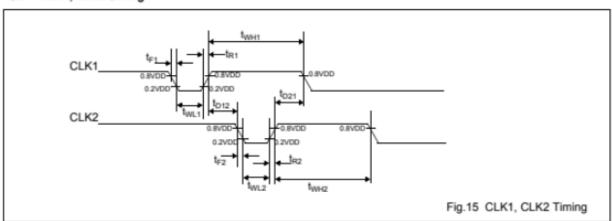


Table 24 CLK1 and CLK2 timing characteristics

 $V_{DD}$  = 5 V ±10%;  $V_{SS}$  = 0 V; all voltages with respect to  $V_{SS}$  unless otherwise specified;  $T_{amb}$  = -20 to +75 °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
T <sub>WH1</sub>	CLK1 clock high pulse width		2000			
T <sub>WL1</sub>	CLK1 cock low pulse width		600			
T <sub>R1</sub>	CLK1 clock rise time				130	
T <sub>F1</sub>	CLK1 clock fall time				130	
T <sub>WH2</sub>	CLK2 clock high pulse width		2000			
T <sub>WL2</sub>	CLK2 clock low pulse width		600			ns
T <sub>R2</sub>	CLK2 clock rise time				130	7
T <sub>F2</sub>	CLK2 clock fall time				130	1
T <sub>D12</sub>	CLK1-to-CLK2 delay		660			7
T <sub>D21</sub>	CLK2-to-CLK1 delay		660			7





# 8. Quality Specification (Continued):

## 8-3. Sampling Plan and Acceptance

## 1. Sampling Plan

MIL - STD - 105E ( **II** ) ordinary single inspection is used.

## 2. Acceptance

Major defect: AQL = 0.25%Minor defect: AQL = 0.65%

#### 8-4. Criteria

#### a) COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

## b) SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift	X < 3/4Z Y > 1/3D	Reject Reject
Minor	soldering pad  Component tilt	Y > 1/3D	Reject



Minor	Insufficient solder  component PAD	θ ≤ 20'	Reject
	PCB		

## c) Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards					
Major	Crack / breakage	Anywher	Reject				
		W	L	Acceptable of Scratch			
		w<0.03mm	Any	Ignore			
		0.03mm <u>&lt;</u> w<0.05mm	L <u>&lt;</u> 5.0mm	2			
Minor	Frame Scratch	0.05mm <w<0.1mm< td=""><td>L&lt;3.0mm</td><td>1</td></w<0.1mm<>	L<3.0mm	1			
		w>0.1mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines w distance greater than 5mm.  2. Scratch on the back side of frame (not visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ <u>&lt;</u> 1.0mr	n	2			
		1.0<⊕ <u>&lt;</u> 1.5	mm	1			
Minor	Frame Dent, Prick	1.5mm> Ф		0			
	$\Phi = \frac{L + W}{2}$	Note: 1. Above criteria pricks with distance gr 2. Dent / prick ovisible) can be ignored	reater than 5m on the back sid	-			
Minor	Frame Deformation	Exceed the dimension of drawing					
Minor	Metal Frame Oxidation	Any rust					



## d) Flexible Film Connector (FFC)

Defect	In	spection Item	Inspection S	tandards
Minor	Tilted soldering		Within the angle ±3°	Acceptable
Minor	Uneven solder joint /bump			Reject
	Hole	L+W	Expose the conductive line	Reject
Minor	поје	2	Φ > 1.0mm	Reject
Minor	Po	sition shift	Y > 1/3D	Reject
WINOT -A		- <del>-</del>	X > 1/2Z	Reject

## e) Screw

Defect Inspection Item		Inspection Standards		
Major	Screw missing/loosen		Reject	
Minor	Screw oxidation	Any rust	Reject	
Minor	Screw deformation	Difficult to accept screw driver	Reject	

## f) Heat seal , TCP , FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ > 0 <mark>.2mm</mark>	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
IVIIIIOI		X > 1/2Z	Reject
Major	Conductive line break		Reject



## g) LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards		
		Acceptable number of units		
		Ф <b>≤</b> 0.10mm		
		0.10<⊕ <u>&lt;</u> 0.15mm		
Minor	LED dirty, prick	0.15<⊅ <u>&lt;</u> 0.2mm	1	
		Ф>0.2mm	0	
		The distance between any two spots should be ≥10mm Any spot/dot/void outside of viewing area is acceptable		
Minor	Protective film tilt	Not fully cover LCD	Reject	
Major	COG coating	Not fully cover ITO circuit	Reject	

## h) Electric Inspection

Defect Inspection Item		Inspection Standards	
Major	Short		Reject
Major	Open		Reject



# i) Inspection Specification of LCD

Defect		Inspect Item				Ins	pect	ion St	anda	ırds
		* Glass Scratch	W		W<0.0			03 <w<0.05< td=""><td>5</td><td>W&gt;0.05</td></w<0.05<>	5	W>0.05
		* Polarizer Scratch	ACC.		L<5		L<3			Any
Minor	Linear Defect		NO.		1			1		Reject
		<ul><li>Fiber and Linear material</li></ul>	Note	L is 1	the lengt	th and W	is the	width of th	e defe	ect
		* Foreign material	Ф	Ф	<u>&lt;</u> 0.1	0.1<⊕≤	0.15	0.15<⊕ <u></u>	≤0.2	Ф>0.2
	Black Spot and	between glass and polarizer or glass	ACC. NO.	3E/	A/1PC	2		1		0
Minor	Polarizer Pricked	* Polarizer hole or protuberance by external force	Note			erage dia > 10mm.	meter	of the defe	ect.Dis	tance between
		* Unobvious	Ф	Ф	<sup>0</sup> <0.1	0.1<⊕ <u>&lt;</u>	<u>&lt;</u> 0.15	0.15<Ф	≤0.2	Ф>0.2
		transparent foreign material between	ACC. NO.	3E.	A/1PC	2		1		0
Minor	White Spot and Bubble in polarizer	glass and glass or glass and polarizer  * Air protuberance between polarizer and glass	Note	Φ is the average diameter of the defect. Distance betweetwo defects > 10mm.				tance between		
			Ф	Ф	<u>&lt;</u> 0.10	0.10<Φ <u>&lt;</u> 0.20				Ф>0.2
		w W	ACC. NO.	3E	A/1PC		2			0
N 4:	Segment			W is more than 1/2 segment width		Reject				
Minor	Defect		Note	Dista	ance bet	ween two		= L + W 2 ct is 10mm		
				đ	<sup>⊅</sup> <0.10	0.10<Φ <u>&lt;</u> 0.20			Φ>0.2	
	Protuberant		W		Glue	W	/ <u>&lt;</u> 1/2	Seg , W <u>&lt;</u> 0.	.2	Ignore
Minor	Segment	Segment $\Phi = (L+W)/2$	ACC. NO.	38	EA/1PC			2		0
				1. Segment						
			В	B <u>&lt;</u> 0.4mm		0.4 <b<1.0mm< td=""><td></td><td>B&gt;1.0mm</td></b<1.0mm<>			B>1.0mm	
			B-A	B-A<1/2B		1/2B				B-A<0.25
Minor	Assembly Mis-			ge Acceptable Acceptable			Acceptable			
	alignment	0.35mm				2	. Dot I	Matrix		
					Deform	nation>0	.35mn	n		Reject



Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the aboveitems: "Black spot" and "White Spot"
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# 9. Reliability:

NO.	Item	Condition	Criterion	
1	High Temperature Operating	70°C, 96Hrs		
2	Low Temperature Operating	-20℃, 96Hrs		
3	High Humidity	40℃, 90%RH, 96Hrs	(R)	
4	High Temperature Storage	80°C, 96Hrs	No defect in	
5	Low Temperature Storage	-30℃, 96Hrs	cosmeticand operational function allowable.	
6	Vibration	Random wave  10 ~ 100Hz  Acceleration: 2g  2 Hrs per direction(X,Y,Z)	Total current Consumption shouldbe below double of initial value.	
7	Thermal Shock	-10°C to 25°C to 60°C (60Min) (5Min) (60Min) 16Cycles		
8	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV	There will be discharged ten times at every discharging voltage	
0	ESD TESHING	Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	cycle. The voltage gap is 1kV.	

*Note:* 1) Above conditions are suitable for xinnuoya standard products.

2) For restrict products, the test conditions listed as above must be revised.



# 10. Handling Precaution:

#### (1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizerswhich easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommendedbelow) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before poweris turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
- Modules use LCD elements, and must be treated as such. Avoid intense shockand falls from a height.
- To prevent modules from degradation. Do not operate or store them exposeddirectly to sunshine or high temperature/humidity.
- (5) Caution for operation
- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.



## **Handling Precaution (Continued):**

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show darkcolor in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 60°C, 90% RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance, for years) for thepurpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is.

  Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
- It is recommendable to crash damaged or unnecessary LCD into pieces and washoff liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact withyour hands, please wash it off well with soap and water.



## 11. Outline Dimensions:

